

Electronic Patent Application Fee Transmittal

Application Number:	10537959
Filing Date:	07-Jun-2005
Title of Invention:	Thermoplastic polyimide resin film, multilayer body and method for manufacturing printed wiring board composed of same
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Filer:	Dariush G. Adli
Attorney Docket Number:	81844.0036

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 3 months with \$0 paid	1253	1	1110	1110

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				1920